

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

APPLICANT: **JOHN F. BREEDIS**
RONALD N. CARON
CARL L. DEPPISCH

Atty. DOCKET: 101-931

SERIAL NO.: 09/192766

FILED: November 16, 1998

ART UNIT: 1742

FOR: "STRESS RELAXATION RESISTANT BRASS"

CERTIFICATE OF MAILING	
I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231	
Date: <u>FEB. 23, 1999</u>	<u>Gregory S. Rosenblatt</u> Name of Person Mailing Paper
<u>[Signature]</u> Signature of Person Mailing Paper	

INFORMATION DISCLOSURE TRANSMITTAL LETTER

ASSISTANT COMMISSIONER FOR PATENTS
U.S. PATENT & TRADEMARK OFFICE
WASHINGTON, D.C. 20231

RECEIVED

MAR 05 1999

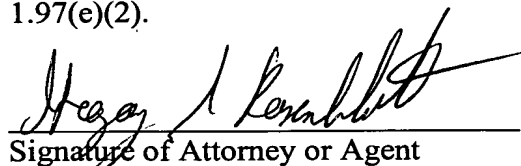
Dear Sir:

GROUP 1700

Pursuant to 37 C.F.R. 1.97, enclosed are an Information Disclosure Statement, Form PTO-1449 and one copy of each reference. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

- [X] 1. The accompanying Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.
- [] 2. The accompanying Information Disclosure Statement is being filed more than three months after the U.S. filing date AND after the mailing date of the first Office Action on the merits, but before the mailing date of a Final Rejection or Notice of Allowance.
- [] a) Each item of information contained in the Information Disclosure Statement filed herewith was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 C.F.R. 1.97(e)(1); and no fee is required under 37 C.F.R. 1.17(p).

- ☐ b) No item of information in the Information Disclosure Statement filed herewith was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 C.F.R. 1.97(e)(2); and no fee is required under 37 C.F.R. 1.17(p).
- ☐ c) Please charge Deposit Account No. 23-1665 in the amount of \$240.00 in payment of the fee under 37 C.F.R. 1.17(p). Two additional copies of this transmittal are enclosed.
- ☐ 3. The accompanying Information Disclosure Statement is being filed more than three months after the U.S. filing date and after the mailing date of a Final Rejection or Notice of Allowance, but before payment of the Issue Fee. It is hereby requested that the Information Disclosure Statement be considered. Please charge Deposit Account No. 23-1665 in the amount of \$130.00 in payment of the fee under 37 C.F.R. 1.17(i)(1). Two additional copies of this transmittal are enclosed.
- ☐ a) Each item of information contained in the Information Disclosure Statement filed herewith was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 C.F.R. 1.97(e)(1).
- ☐ b) No item of information in the Information Disclosure Statement filed herewith was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge after making reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this Information Disclosure Statement. 37 C.F.R. 1.97(e)(2).

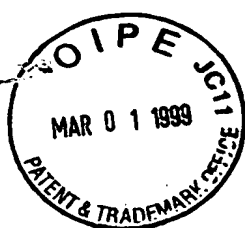

Signature of Attorney or Agent

Gregory S. Rosenblatt
Name of Attorney or Agent
Reg. No. 32,489

Tel. No.: (203) 498-4566

Date: FEB. 23, 1999

WIGGIN & DANA
ONE CENTURY TOWER
NEW HAVEN, CT 06508-1832



**IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE**

GP 1742
SADH
#2
3-12-99

APPLICANT: **JOHN F. BREEDIS
RONALD N. CARON
CARL L. DEPPISCH**

Atty. DOCKET: 101-931

SERIAL NO.: 09/192,766

FILED: November 16, 1998

ART UNIT: 1742

FOR: "STRESS RELAXATION RESISTANT BRASS"

CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231

Date: FEB. 23, 1999

Gregory S. Rosenblatt

Name of Person Mailing Paper

Gregory S. Rosenblatt
Signature of Person Mailing Paper

INFORMATION DISCLOSURE STATEMENT

RECEIVED

HON. COMMISSIONER FOR PATENTS
U.S. PATENT & TRADEMARK OFFICE
WASHINGTON, D.C. 20231

MAR 05 1999

GROUP 1700

Dear Sir:

In keeping with the duty of candor and good faith owed to the Patent and Trademark Office, applicant wishes to make of record the items on attached PTO Form 1449 which were considered during the preparation of the subject application. Copies of the items are provided in accordance with 37 CFR 1.98.

U.S. Patent No. 2,028,317 entitled "Welding Rod Alloy" by Butterbaugh issued January 21, 1936.

U.S. Patent No. 3,375,107 entitled "Copper Base Alloy and Method for Its Manufacture" by Kranz issued March 26, 1968.

U.S. Patent No. 4,337,089 entitled "Copper-Nickel-Tin Alloys for Lead Conductor Materials for Integrated Circuits and a Method for Producing the Same" by Arita, et al. issued June 29, 1982.

U.S. Patent No. 4,362,579 entitled "High-Strength-Conductivity Copper Alloy" by Tsuji issued December 7, 1982.

U.S. Patent No. 4,666,667 entitled "High-Strength, High-Conductivity Copper Alloy" by Kamio, et al. issued May 19, 1987.

U.S. Patent No. 4,971,758 entitled "Copper-Based Alloy Connector for Electrical Devices" by Suzuki, et al. issued November 20, 1990.

U.S. Patent No. 5,024,814 entitled "Copper Alloy Having Excellent Hot Rollability and Excellent Adhesion Strength of Plated Surface Thereof when Heated" by Futatasuka, et al. issued June 18, 1991.

U.S. Patent No. 5,334,346 entitled "Copper Alloy for Electrical and Electronic Parts" by Kim issued August 2, 1994.

U.S. Patent No. 5,507,885 entitled "Copper-Based Alloy" by Sakai issued April 16, 1996.

U.S. Patent No. 5,820,701 entitled "Copper Alloy and Process for Obtaining Same" by Bhargava issued October 13, 1998.

U.S. Patent No. 5,865,910 entitled "Copper Alloy and Process for Obtaining Same" by Bhargava issued February 2, 1999.

The following foreign patents were also considered during the preparation of the application:

Japan – Patent No.59047751, published March 17, 1984. A Derwent abstract (copy enclosed) details a copper alloy comprising 1.5 – 10 wt% Ni, 5 – 20 wt% Zn, 0.0020 wt% O and balance copper and impurities.

Japan – Patent No.59126742, published July 21, 1984. A Derwent abstract (copy enclosed) details a copper alloy useful as the welded tube of radiator.

Japan – Patent No.59197542, published November 9, 1984. A Derwent abstract (copy enclosed) details an alloy useful for radiator tubes exposed to corrosive atmosphere.

Japan – Patent No.61127840, published November 27, 1984. A Derwent abstract (copy enclosed) details a Cu alloy used for electrically conductive spring materials such as connectors, terminals, relays, and switches, as well as lead materials of semiconductor equipment such as transistors and integrated circuits.

Japan – Patent No.62199741, published September 3, 1987. A Derwent abstract (copy enclosed) details a Cu alloy used for the terminals or connectors of civil, industrial applications, and automobiles.

Japan – Patent No.63026320, published February 3, 1988. A Derwent abstract (copy enclosed) details a Cu alloy with excellent spring properties and corrosion resistance.

Japan – Patent No.1062429, published March 8, 1989. A Derwent abstract (copy enclosed) details a bus bar for an electric connection box made of Cu alloy.

Japan – Patent No.1068436, published March 14, 1989. A Derwent abstract (copy enclosed) details a heat resistant Cu alloy bar.

Japan – Patent No.4354843, published December 9, 1992. A Derwent abstract (copy enclosed) details a Cu alloy used for manufacturing heat exchangers, etc.

Japan – Patent No.5311292, published November 22, 1993. A Derwent abstract (copy enclosed) details a Cu-based alloy used for car radiators and domestic heat exchangers.

Japan – Patent No.6184679, published July 5, 1994. A Derwent abstract (copy enclosed) details a Cu alloy used for connectors and other lead material, having good strength, heat resistance and spring limiting value.

Japan – Patent No.7126779, published May 16, 1995. A Derwent abstract (copy enclosed) details a Cu alloy used for multi-pin connectors and sockets for charging electric cars.

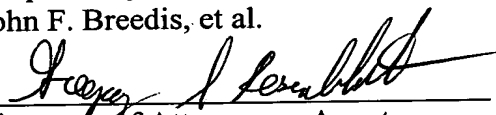
EP - 0-795-693-A2 entitled "Copper-alloy and sliding bearing having improved seizure resistance" by Oshiro et al., published Sep. 17, 1997.

EP – 0-859-065-A1 entitled "Copper base alloys and terminals using the same" by Hana et al., published Aug. 19, 1998.

The following publication was also considered during preparation of the application:

Bhargava, New Higher Conductivity Alloys Within the Improved Phosphor Bronze and Improved Copper-Tin-Zinc Alloy Families, pages 119-129.

Respectfully submitted,
John F. Breedis, et al.



Signature of Attorney or Agent

Gregory S. Rosenblatt
Name of Attorney or Agent
Reg. No. 32,489

Tel. No.: (203) 498-4566

Date: February 13, 1999

WIGGIN & DANA
ONE CENTURY TOWER
NEW HAVEN, CT 06508-1832